



# 20-3037 LOW DENSITY EPOXY ADHESIVE/SEALANT

## DESCRIPTION:

20-3037 is a low density, two component epoxy bonding and sealing system. The 20-3037 is less than half the weight of most commercially available potting compounds. 20-3037 exhibits very low shrinkage during the cure cycle and also has a low coefficient of thermal expansion. This unique epoxy system is ideal where a low dielectric constant and low weight are required.

This epoxy syntactic foam system utilizes an advanced micro balloon technology filler. The 20-3037 provides high strength and stiffness, thermal and environmental stability, creep resistance, and water resistance.

## FEATURES:

- Low Dielectric Constant
- Low Coefficient of Thermal Expansion
- Low Shrinkage
- Low Density
- Excellent Moisture Resistance

## TYPICAL SPECIFICATIONS:

Viscosity resin, 25°C, cps	Non-Sag Paste
Specific gravity, @ 25°C	0.82
Pot life, 100 gram mass, @ 25°C	45 Min.
Hardness, Shore D	80D
Flexural strength, psi	7,000
Compressive strength, psi	12,000
Tensile strength, psi	3,000
Linear shrinkage, in/in	0.001
Water absorption, % (24 hr.)	0.13
Coefficient of thermal expansion, °C	43x10 <sup>-6</sup>
Thermal conductivity, W/m- °K	0.18
Operating temperature, °C	-40 to +130
Outgassing	
% TMLV	0.46
%CVCM	0.06

**TYPICAL SPECIFICATIONS (continued):**

Dielectric strength, V/mil	375
Dielectric constant, 1 MHz	2.70
Dissipation factor, 1 MHz	.05
Volume resistivity, ohm-cm @ 25°C	>10 <sup>13</sup>
Mix ratio by weight (Resin: Catalyst)	100:10.3
Mix ratio by volume	100: 9

**MIXING INSTRUCTIONS:**

**ROOM TEMPERATURE CURING CATALYST 190:**

- 1) By weight thoroughly mix 10.3 parts Catalyst 190 to 100 parts 20-3037 Resin.
- 2) Apply and cure according to one of the following cure schedules:
  - a) 25°C                      16-24 Hours
  - b) 45°C                      4-6 Hours
  - c) 65°C                      1-2 Hours

**IMPORTANT:**

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